# EEPROM Serial 16-Kb I<sup>2</sup>C

# Description

The CAT24AA16 is a EEPROM Serial 16–Kb I<sup>2</sup>C device internally organized as 2048x8 bits.

The device features a 16-byte page write buffer and supports 100 kHz, 400 kHz and 1 MHz  $1^2\text{C}$  protocols.

Data is written by providing a starting address, then loading 1 to 16 contiguous bytes into a Page Write Buffer, and then writing all data to non-volatile memory in one internal write cycle. Data is read by providing a starting address and then shifting out data serially while automatically incrementing the internal address count.

### **Features**

- Standard and Fast I<sup>2</sup>C Protocol Compatible
- Supports 1 MHz Clock Frequency
- 1.7 V to 5.5 V Supply Voltage Range
- 16-Byte Page Write Buffer
- Hardware Write Protection for Entire Memory
- Schmitt Triggers and Noise Suppression Filters on I<sup>2</sup>C Bus Inputs (SCL and SDA)
- Low Power CMOS Technology
- 1,000,000 Program/Erase Cycles
- 100 Year Data Retention
- Industrial Temperature Range
- This Device is Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

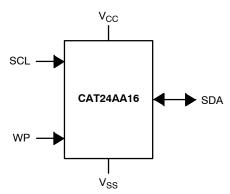


Figure 1. Functional Symbol



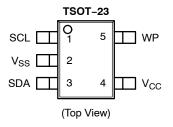
# ON Semiconductor®

www.onsemi.com



TSOT-23 TB SUFFIX CASE 419AE

## **PIN CONFIGURATIONS**



# **PIN FUNCTION**

Function			
Serial Data Input/Output			
Clock Input			
Write Protect			
Power Supply			
Ground			
No Connect			

### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 203 of this data sheet.

### **Table 1. ABSOLUTE MAXIMUM RATINGS**

Parameters	Ratings	Units
Storage Temperature	-65 to +150	°C
Voltage on any Pin with Respect to Ground (Note 1)	-0.5 to +6.5	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### Table 2. REABILITY CHARACTERISTICS (Note 2)

Symbol	Parameter	Min	Units
N <sub>END</sub> (Note 3)	Endurance	1,000,000	Program/Erase Cycles
T <sub>DR</sub>	Data Retention	100	Years

These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.

Table 3. DC OPERATING CHARACTERISTICS (V<sub>CC</sub> = 1.7 V to 5.5 V, T<sub>A</sub> = -40°C to 85°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	Min	Max	Units
I <sub>CCR</sub>	Read Current	Read, f <sub>SCL</sub> = 400 kHz		0.5	mA
I <sub>CCW</sub>	Write Current	Write, f <sub>SCL</sub> = 400 kHz		1	mA
I <sub>SB</sub>	Standby Current	All I/O Pins at GND or V <sub>CC</sub>		1	μΑ
IL	I/O Pin Leakage	Pin at GND or V <sub>CC</sub>		1	μΑ
V <sub>IL</sub>	Input Low Voltage		-0.5	V <sub>CC</sub> x 0.3	V
V <sub>IH</sub>	Input High Voltage		V <sub>CC</sub> x 0.7	V <sub>CC</sub> + 0.5	V
V <sub>OL1</sub>	Output Low Voltage	$V_{CC} \ge 2.5 \text{ V}, I_{OL} = 3.0 \text{ mA}$		0.4	V
V <sub>OL2</sub>	Output Low Voltage	V <sub>CC</sub> < 2.5 V, I <sub>OL</sub> = 1.0 mA		0.2	V

Table 4. PIN IMPEDANCE CHARACTERISTICS (V<sub>CC</sub> = 1.7 V to 5.5 V, T<sub>A</sub> = -40°C to 85°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Max	Units
C <sub>IN</sub> (Note 4)	SDA I/O Pin Capacitance	V <sub>IN</sub> = 0 V	8	pF
C <sub>IN</sub> (Note 4)	Input Capacitance (Other Pins)	V <sub>IN</sub> = 0 V	6	pF
I <sub>WP</sub> (Note 5)	WP Input Current	$V_{IN} < 0.5 \text{ x } V_{CC}, V_{CC} = 5.5 \text{ V}$	200	μΑ
		$V_{IN} < 0.5 \times V_{CC}, V_{CC} = 3.3 \text{ V}$	150	
		V <sub>IN</sub> < 0.5 x V <sub>CC</sub> , V <sub>CC</sub> = 1.8 V	100	
		V <sub>IN</sub> > 0.5 x V <sub>CC</sub>	1	

These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.

<sup>1.</sup> The DC input voltage on any pin should not be lower than -0.5 V or higher than  $V_{CC} + 0.5$  V. During transitions, the voltage on any pin may undershoot to no less than -1.5 V or overshoot to no more than  $V_{CC} + 1.5$  V, for periods of less than 20 ns.

<sup>3.</sup> Page Mode @ 25°C

<sup>5.</sup> When not driven, the WP pin is pulled down to GND internally. For improved noise immunity, the internal pull-down is relatively strong; therefore the external driver must be able to supply the pull-down current when attempting to drive the input HIGH. To conserve power, as the input level exceeds the trip point of the CMOS input buffer (~ 0.5 x V<sub>CC</sub>), the strong pull-down reverts to a weak current source.

Table 5. AC CHARACTERISTICS (Note 6) ( $V_{CC}$  = 1.7 V to 5.5 V,  $T_A$  = -40°C to 85°C, unless otherwise specified.)

		Standard V <sub>CC</sub> = 1.7 V - 5.5 V			ast 7 V – 5.5 V	1 MHz V <sub>CC</sub> = 2.5 V - 5.5 V		
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Units
F <sub>SCL</sub>	Clock Frequency		100		400		1000	kHz
t <sub>HD:STA</sub>	START Condition Hold Time	4		0.6		0.25		μs
t <sub>LOW</sub>	Low Period of SCL Clock	4.7		1.3		0.4		μs
t <sub>HIGH</sub>	High Period of SCL Clock	4		0.6		0.4		μs
t <sub>SU:STA</sub>	START Condition Setup Time	4.7		0.6		0.25		μs
t <sub>HD:DAT</sub>	Data In Hold Time	0		0		0		ns
t <sub>SU:DAT</sub>	Data In Setup Time	250		100		100		ns
t <sub>R</sub> (Note 7)	SDA and SCL Rise Time		1000		300		300	ns
t <sub>F</sub> (Note 7)	SDA and SCL Fall Time		300		300		100	ns
t <sub>SU:STO</sub>	STOP Condition Setup Time	4		0.6		0.25		μs
t <sub>BUF</sub>	Bus Free Time Between STOP and START	4.7		1.3		0.5		μs
t <sub>AA</sub>	SCL Low to Data Out Valid		3.5		0.9		0.4	μs
t <sub>DH</sub>	Data Out Hold Time	100		50		50		ns
T <sub>i</sub> (Note 7)	Noise Pulse Filtered at SCL and SDA Inputs		100		100		100	ns
t <sub>SU:WP</sub>	WP Setup Time	0		0		0		μs
t <sub>HD:WP</sub>	WP Hold Time	2.5		2.5		1		μs
t <sub>WR</sub>	Write Cycle Time		5		5		5	ms
t <sub>PU</sub> (Notes 7, 8)	Power-up to Ready Mode		1		1		1	ms

# Table 6. A.C. TEST CONDITIONS

Input Levels	0.2 x V <sub>CC</sub> to 0.8 x V <sub>CC</sub>
Input Rise and Fall Times	≤ 50 ns
Input Reference Levels	0.3 x V <sub>CC</sub> , 0.7 x V <sub>CC</sub>
Output Reference Levels	0.5 x V <sub>CC</sub>
Output Load	Current Source: $I_{OL}$ = 3 mA ( $V_{CC} \ge 2.5$ V); $I_{OL}$ = 1 mA ( $V_{CC}$ < 2.5 V); $C_L$ = 100 pF

<sup>6.</sup> Test conditions according to "AC Test Conditions" table.
7. Tested initially and after a design or process change that affects this parameter.
8. t<sub>PU</sub> is the delay between the time V<sub>CC</sub> is stable and the device is ready to accept commands.

# Power-On Reset (POR)

Each CAT24AA16 incorporates Power–On Reset (POR) circuitry which protects the internal logic against powering up in the wrong state. The device will power up into Standby mode after  $V_{CC}$  exceeds the POR trigger level and will power down into Reset mode when  $V_{CC}$  drops below the POR trigger level.

This bi-directional POR behavior protects the device against brown-out failure, following a temporary loss of power.

# **Pin Description**

**SCL**: The Serial Clock input pin accepts the clock signal generated by the Master.

**SDA**: The Serial Data I/O pin accepts input data and delivers output data. In transmit mode, this pin is open drain. Data is acquired on the positive edge, and delivered on the negative edge of SCL.

**WP**: When the Write Protect input pin is forced HIGH by an external source, all write operations are inhibited. When the pin is not driven by an external source, it is pulled LOW internally.

## **Functional Description**

The CAT24AA16 supports the Inter–Integrated Circuit (I<sup>2</sup>C) Bus protocol. The protocol relies on the use of a Master device, which provides the clock and directs bus traffic, and Slave devices which execute requests. The CAT24AA16 operates as a Slave device. Both Master and Slave can transmit or receive, but only the Master can assign those roles.

### I<sup>2</sup>C Bus Protocol

The 2-wire  $I^2C$  bus consists of two lines, SCL and SDA, connected to the  $V_{CC}$  supply via pullup resistors. The Master provides the clock to the SCL line, and the Master and Slaves drive the SDA line. A '0' is transmitted by pulling a line LOW and a '1' by releasing it HIGH. Data transfer may be initiated only when the bus is not busy (see AC Characteristics). During data transfer, SDA must remain stable while SCL is HIGH.

# **START/STOP Condition**

An SDA transition while SCL is HIGH creates a START or STOP condition (Figure 2). A START is generated by a HIGH to LOW transition, while a STOP is generated by a LOW to HIGH transition. The START acts like a wake-up call. Absent a START, no Slave will respond to the Master. The STOP completes all commands.

## **Device Addressing**

The Master addresses a Slave by creating a START condition and then broadcasting an 8-bit Slave address (Figure 3). The four most significant bits of the Slave address are 1010 (Ah). The next three bits are internal address bits,  $a_{10}$ ,  $a_{9}$ ,  $a_{8}$ . The last bit,  $R/\overline{W}$ , instructs the Slave to either provide (1) or accept (0) data, i.e. it specifies a Read (1) or a Write (0) operation.

# Acknowledge

During the 9<sup>th</sup> clock cycle following every byte sent onto the bus, the transmitter releases the SDA line, allowing the receiver to respond. The receiver then either acknowledges (ACK) by pulling SDA LOW, or does not acknowledge (NoACK) by letting SDA stay HIGH (Figure 4). Bus timing is illustrated in Figure 5.

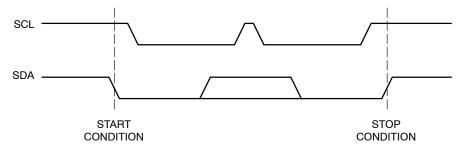


Figure 2. Start/Stop Timing

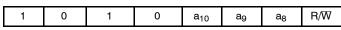


Figure 3. Slave Address Bits

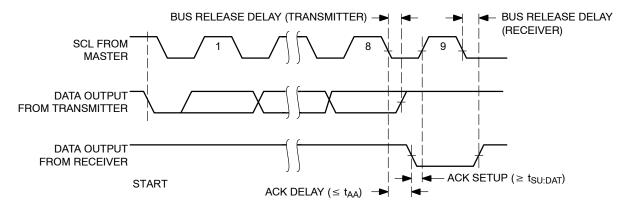


Figure 4. Acknowledge Timing

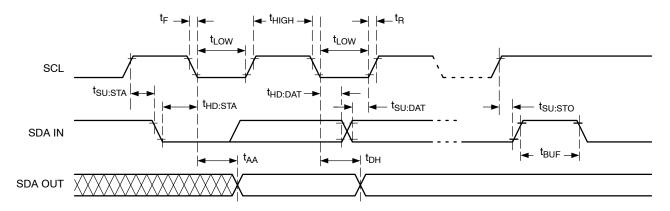


Figure 5. Bus Timing

## WRITE OPERATIONS

# **Byte Write**

To write data to memory, the Master creates a START condition on the bus and then broadcasts a Slave address with the R/W bit set to '0'. The Master then sends an address byte and a data byte and concludes the session by creating a STOP condition on the bus. The Slave responds with ACK after every byte sent by the Master (Figure 6). The STOP starts the internal Write cycle, and while this operation is in progress (t<sub>WR</sub>), the SDA output is tri–stated and the Slave does not acknowledge the Master (Figure 7).

### **Page Write**

The Byte Write operation can be expanded to Page Write, by sending more than one data byte to the Slave before issuing the STOP condition (Figure 8). Up to 16 distinct data bytes can be loaded into the internal Page Write Buffer starting at the address provided by the Master. The page address is latched, and as long as the Master keeps sending data, the internal byte address is incremented up to the end of page, where it then wraps around (within the page). New data can therefore replace data loaded earlier. Following the STOP, data loaded during the Page Write session will be written to memory in a single internal Write cycle (twR).

# **Acknowledge Polling**

The acknowledge (ACK) polling routine can be used to take advantage of the typical write cycle time. Once the stop condition is issued to indicate the end of the host's write operation, the CAT24AA16 initiates the internal write cycle. The ACK polling can be initiated immediately. This involves issuing the start condition followed by the slave address for a write operation. If the CAT24AA16 is still busy with the write operation, NoACK will be returned. If the CAT24AA16 device has completed the internal write operation, an ACK will be returned and the host can then proceed with the next read or write operation.

# **Hardware Write Protection**

With the WP pin held HIGH, the entire memory is protected against Write operations. If the WP pin is left floating or is grounded, it has no impact on the Write operation. The state of the WP pin is strobed on the last falling edge of SCL immediately preceding the 1<sup>st</sup> data byte (Figure 9). If the WP pin is HIGH during the strobe interval, the Slave will not acknowledge the data byte and the Write request will be rejected.

## **Delivery State**

The CAT24AA16 is shipped erased, i.e., all bytes are FFh.

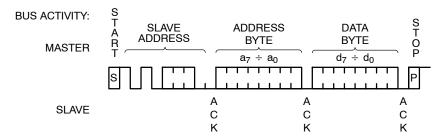


Figure 6. Byte Write Sequence

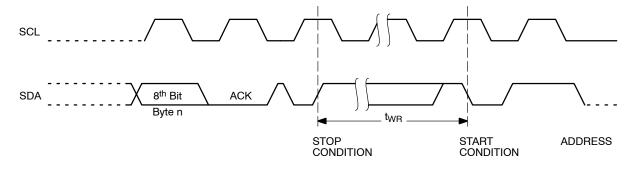


Figure 7. Write Cycle Timing

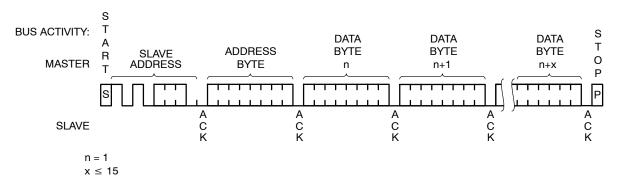


Figure 8. Page Write Sequence

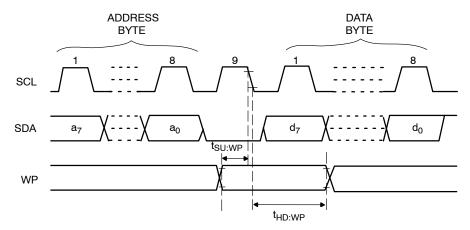


Figure 9. WP Timing

### **READ OPERATIONS**

### **Immediate Read**

To read data from memory, the Master creates a START condition on the bus and then broadcasts a Slave address with the R/W bit set to '1'. The Slave responds with ACK and starts shifting out data residing at the current address. After receiving the data, the Master responds with NoACK and terminates the session by creating a STOP condition on the bus (Figure 10). The Slave then returns to Standby mode.

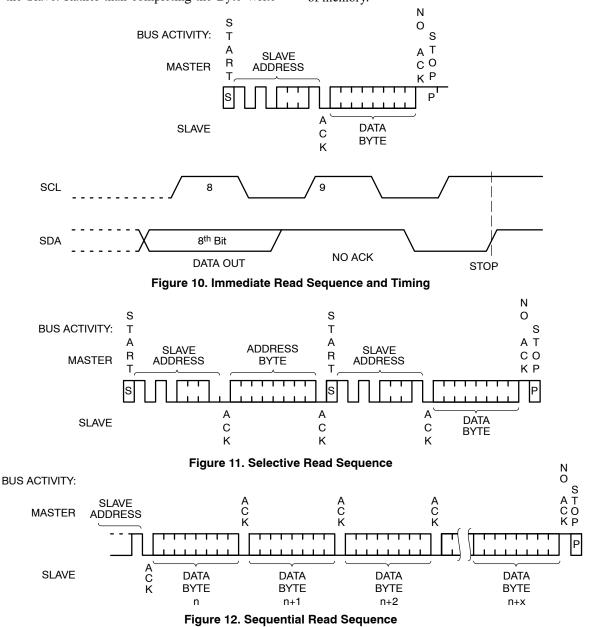
### **Selective Read**

To read data residing at a specific address, the selected address must first be loaded into the internal address register. This is done by starting a Byte Write sequence, whereby the Master creates a START condition, then broadcasts a Slave address with the R/W bit set to '0' and then sends an address byte to the Slave. Rather than completing the Byte Write

sequence by sending data, the Master then creates a START condition and broadcasts a Slave address with the R/W bit set to '1'. The Slave responds with ACK after every byte sent by the Master and then sends out data residing at the selected address. After receiving the data, the Master responds with NoACK and then terminates the session by creating a STOP condition on the bus (Figure 11).

## **Sequential Read**

If, after receiving data sent by the Slave, the Master responds with ACK, then the Slave will continue transmitting until the Master responds with NoACK followed by STOP (Figure 12). During Sequential Read the internal byte address is automatically incremented up to the end of memory, where it then wraps around to the beginning of memory.



# **ORDERING INFORMATION**

Device Order Number	Specific Device Marking	Package Type	Temperature Range (Note 24)	Lead Finish	Shipping†
CAT24C02TDI-GT3	UK	TSOT-23-5	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ON Semiconductor is licensed by the Philips Corporation to carry the  $I^2C$  bus protocol.

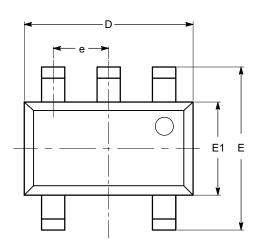
All packages are RoHS-compliant (Lead-free, Halogen-free).
 The standard lead finish is NiPdAu.

<sup>11.</sup> For additional package and temperature options, please contact your nearest ON Semiconductor Sales office.

<sup>12.</sup> For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

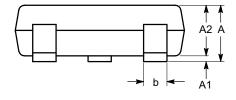
TSOT-23, 5 LEAD CASE 419AE-01 ISSUE O

**DATE 19 DEC 2008** 

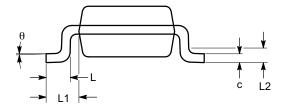


SYMBOL	MIN	NOM	MAX
Α			1.00
A1	0.01	0.05	0.10
A2	0.80	0.87	0.90
b	0.30		0.45
С	0.12	0.15	0.20
D	2.90 BSC		
Е	2.80 BSC		
E1	1.60 BSC		
е		0.95 TYP	
L	0.30	0.40	0.50
L1	0.60 REF		
L2	0.25 BSC		
θ	0°		8°





SIDE VIEW



**END VIEW** 

## Notes:

- (1) All dimensions are in millimeters. Angles in degrees.(2) Complies with JEDEC MO-193.

DOCUMENT NUMBER:	98AON34392E	Electronic versions are uncontrolled except whe	
STATUS:	ON SEMICONDUCTOR STANDARD	accessed directly from the Document Repository. Print versions are uncontrolled except when stamped	
REFERENCE:		"CONTROLLED COPY" in red.	
DESCRIPTION:	TSOT-23, 5 LEAD	PAGE 1 OF	: 2

				_
	Cam	·ioo:	nd	ctor®
UN	Jell	HGU	IIuu	CLUI



DOCUMENT NUMBER: 98AON34392E

PAGE 2 OF 2

ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION FROM POD #TSOT235-005-01 TO ON SEMICONDUCTOR. REQ. BY B. BERGMAN.	19 DEC 2008

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdt/Patent-Marking.pdf">www.onsemi.com/site/pdt/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and severage may be accessed at <a href="www.onsemi.com/site/pdt/Patent-Marking.pdf">www.onsemi.com/site/pdt/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON

# **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative